


PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/19/11298	
1.3 Title of PCN	STM32WB55 products improvements	
1.4 Product Category	STM32WB55 products	
1.5 Issue date	2019-04-01	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	TSMC T14F Taiwan

4. Description of change

	Old	New
4.1 Description	limitations described in PCN11298 additional document (2.2.10) SMPS not calibrated in production (2.2.11) Wrong data returned when following an access to PWRCTRLR (2.2.12) Secure Flash memory and RSS can be cleared by Cortex M4 application or debug tools (2.2.13) CPU1 cannot access the DBGMCU register if the Debugger probe is not attached (2.3.1) RF reference voltage non-functional at high VDD or at low temperature (2.3.2) RF slot lost due to RF PLL calibration algorithm error (2.3.3) BLE receiver extra power consumption (2.3.4) BLE ADV Stop due to RF PLL VCO amplitude calibration and FSM error	limitations described in PCN11298 additional document are fixed (2.2.10) SMPS not calibrated in production (2.2.11) Wrong data returned when following an access to PWRCTRLR (2.2.12) Secure Flash memory and RSS can be cleared by Cortex M4 application or debug tools (2.2.13) CPU1 cannot access the DBGMCU register if the Debugger probe is not attached (2.3.1) RF reference voltage non-functional at high VDD or at low temperature (2.3.2) RF slot lost due to RF PLL calibration algorithm error (2.3.3) BLE receiver extra power consumption (2.3.4) BLE ADV Stop due to RF PLL VCO amplitude calibration and FSM error
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Function: improvements are indicated in PCN11298 additional document.	

5. Reason / motivation for change

5.1 Motivation	The strategy of ST MCD Division is to increase the robustness and improve performances, quality and functionality of our products. This is achieved by introducing new die revision for STM32WB55 products.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	The die revision changes from "B" to "Y". It is marked on packages of the part.
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7. Timing / schedule

7.1 Date of qualification results	2019-02-05
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7.2 Intended start of delivery	2019-06-19
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	11298 PCN11298_Die_495XXXY_Qualification_plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2019-04-01

9. Attachments (additional documentations)	
11298 Public product.pdf 11298 PCN11298_Die_495XXXY_Qualification_plan.pdf 11298 PCN11298_Additional information.pdf	

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32WB55CEU6	

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Public Products List

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PCN Title : STM32WB55 products improvements

PCN Reference : MDG/19/11298

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32WB55CEU6	STM32WB55RGV7TR	STM32WB55RGV7
STM32WB55CCU6TR		



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